



N-Channel 40 V (D-S) MOSFET

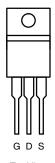
PRODUCT SUMMARY				
V _{DS} (V)	$R_{DS(on)}(\Omega)$	I _D (A) ^d	Q _g (Typ.)	
40	0.0033 at $V_{GS} = 10 \text{ V}$	90	87	
40	0.0041 at $V_{GS} = 4.5 \text{ V}$	90	07	

FEATURES

- Halogen-free According to IEC 61249-2-21 **Definition**
- TrenchFET® Power MOSFET
- 100 % R_a and UIS Tested
- Compliant to RoHS Directive 2002/95/EC



TO-220AB

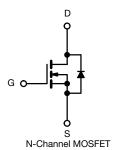


Top View

Ordering Information: SUP90N04-3m3P-GE3 (Lead (Pb)-free and Halogen-free)

APPLICATIONS

- **Power Supply**
 - Secondary Synchronous Rectification
- DC/DC Converter



ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C, unless otherwise noted)					
Parameter	Symbol	Limit	Unit		
Drain-Source Voltage	V _{DS}	40	V		
Gate-Source Voltage		V _{GS}	± 20	v	
Continuous Drain Current (T _{.I} = 150 °C)	T _C = 25 °C	1-	90 ^d		
Continuous Diain Curient (1) = 130 C)	T _C = 70 °C	I _D	90 ^d	A	
Pulsed Drain Current		I _{DM}	160	^	
Avalanche Current		I _{AS}	60		
Single Avalanche Energy ^a	L = 0.1 mH	E _{AS}	180	mJ	
M	T _C = 25 °C	В	125 ^b	10/	
Maximum Power Dissipation ^a	T _A = 25 °C ^c	P_{D}	3.1	W	
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 150	°C	

THERMAL RESISTANCE RATINGS				
Parameter	Symbol	Limit	Unit	
Junction-to-Ambient (PCB Mount) ^c	R _{thJA}	40	°C/W	
Junction-to-Case (Drain)	R _{thJC}	1		

Notes:

- a. Duty cycle \leq 1 %.
- b. See SOA curve for voltage derating.
- c. When mounted on 1" square PCB (FR-4 material).
- d. Package limited.

SUP90N04-3m3P

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Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V_{DS}	$V_{DS} = 0 \text{ V}, I_{D} = 250 \mu\text{A}$	40			V	
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 250 \mu A$	1		2.5	V	
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 250	nA	
		V _{DS} = 40 V, V _{GS} = 0 V			1		
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 40 V, V _{GS} = 0 V, T _J = 125 °C			50	μΑ	
		$V_{DS} = 40 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 150 ^{\circ}\text{C}$			250		
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 10 \text{ V}, V_{GS} = 10 \text{ V}$	50			Α	
	В	V _{GS} = 10 V, I _D = 22 A		0.0027	0.0033		
Drain-Source On-State Resistance ^a	R _{DS(on)}	$V_{GS} = 4.5 \text{ V}, I_D = 20 \text{ A}$		0.0034	0.0041	Ω	
Forward Transconductance ^a	9 _{fs}	V _{DS} = 15 V, I _D = 20 A		169		S	
Dynamic ^b				•			
Input Capacitance	C _{iss}			5286		pF	
Output Capacitance	C _{oss}	$V_{GS} = 0 \text{ V}, V_{DS} = 20 \text{ V}, f = 1 \text{ MHz}$		705			
Reverse Transfer Capacitance	C _{rss}			283			
Total Gate Charge ^c	Q_g			87	131	nC	
Gate-Source Charge ^c	Q_{gs}	$V_{DS} = 20 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 20 \text{ A}$		15.3			
Gate-Drain Charge ^c	Q_{gd}			12.2			
Gate Resistance	R_{g}	f = 1 MHz	0.5	2.7	5.4	Ω	
Turn-On Delay Time ^c	t _{d(on)}			11	20		
Rise Time ^c	t _r	V_{DD} = 20 V, R_L = 2 Ω		7	14		
Turn-Off Delay Time ^c	t _{d(off)}	$I_D \cong 10 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$		45	68	ns	
Fall Time ^c	t _f			7	14		
Drain-Source Body Diode Ratings ar	nd Characteris	stics T _C = 25 °C ^b		•			
Continuous Current	I _S				90		
Pulsed Current	I _{SM}			1	160	Α	
Forward Voltage ^a	V _{SD}	I _F = 10 A, V _{GS} = 0 V		0.72	1.2	V	
Reverse Recovery Time	t _{rr}			42	63	ns	
Peak Reverse Recovery Current	I _{RM(REC)}	$I_F = 10 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}$		2.5	3.8	Α	
Reverse Recovery Charge	Q _{rr}			52	78	nC	

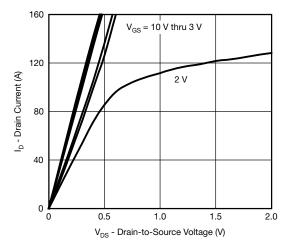
Notes:

- a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 %.
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

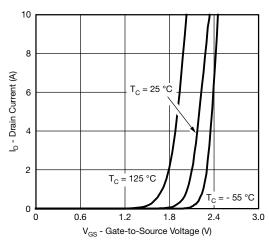
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



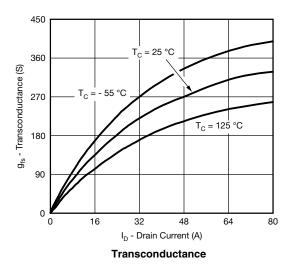
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

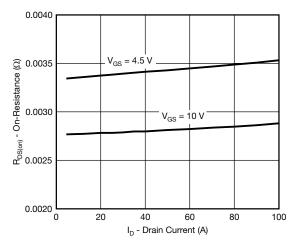


Output Characteristics

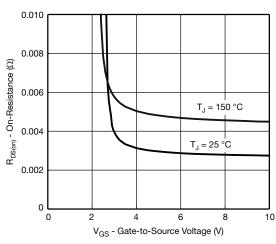


Transfer Characteristics

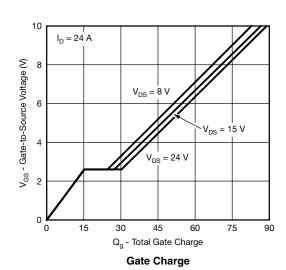




On-Resistance vs. Drain Current

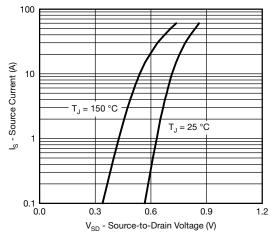


On-Resistance vs. Gate-to-Source Voltage

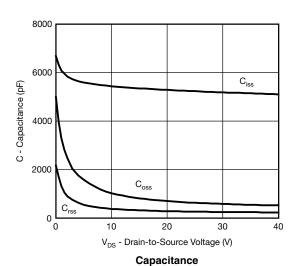


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TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

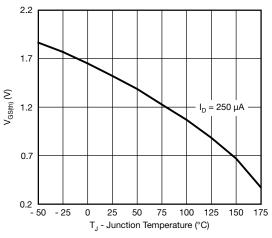


Source-Drain Diode Forward Voltage

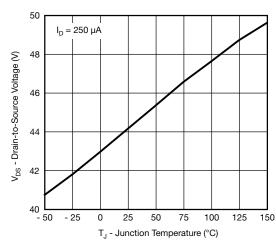


2.0 I_D = 22 A $V_{GS} = 10 \text{ V}$ R_{DS(on)} - On-Resistance (Normalized) 1.7 1.4 $V_{GS} = 4.5 \text{ V}$ 0.5 - 50 - 25 100 125 75 T_J - Junction Temperature (°C)

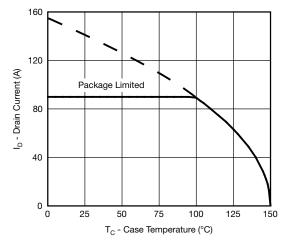
On-Resistance vs. Junction Temperature



Threshold Voltage



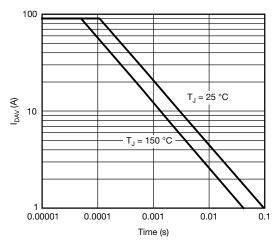
Drain Source Breakdown vs. Junction Temperature

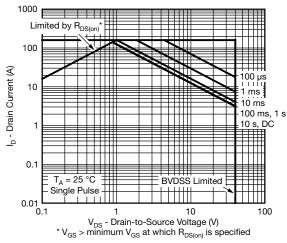


Current Derating

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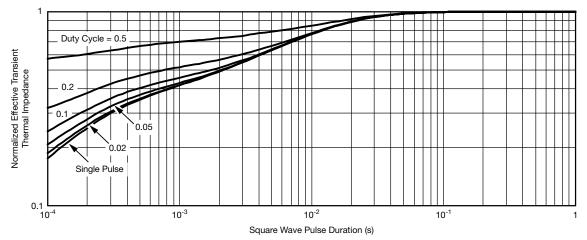
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)





Single Pulse Avalanche Current Capability vs. Time





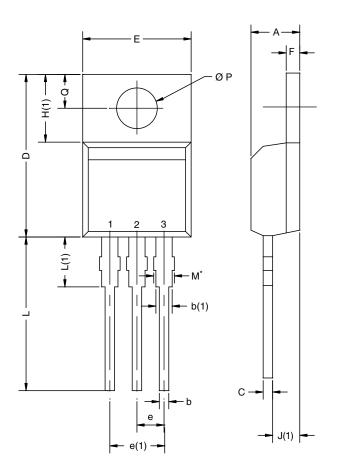
Normalized Thermal Transient Impedance, Junction-to-Case

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see www.vishay.com/ppg?65902.





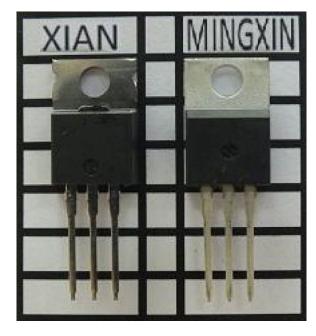
TO-220AB



	MILLIMETERS		INCHES		
DIM.	MIN.	MAX.	MIN.	MAX.	
Α	4.25	4.65	0.167	0.183	
b	0.69	1.01	0.027	0.040	
b(1)	1.20	1.73	0.047	0.068	
С	0.36	0.61	0.014	0.024	
D	14.85	15.49	0.585	0.610	
Е	10.04	10.51	0.395	0.414	
е	2.41	2.67	0.095	0.105	
e(1)	4.88	5.28	0.192	0.208	
F	1.14	1.40	0.045	0.055	
H(1)	6.09	6.48	0.240	0.255	
J(1)	2.41	2.92	0.095	0.115	
L	13.35	14.02	0.526	0.552	
L(1)	3.32	3.82	0.131	0.150	
ØР	3.54	3.94	0.139	0.155	
Q	2.60	3.00	0.102	0.118	

Notes

- * M = 1.32 mm to 1.62 mm (dimension including protrusion) Heatsink hole for HVM
- · Xi'an and Mingxin actual photo





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Revision: 02-Oct-12 Document Number: 91000